

ORDERING INFORMATION

PART NUMBER CODING INTERPRETATION

Position	1	2	3	4	5	6	7	8
1 Product								
AK = Accuthek Memory								
2 Type								
4 = Dynamic RAM								
5 = CMOS Dynamic RAM								
6 = Static RAM								
3 Organization/Word Width								
1 = by 1 16 = by 16								
4 = by 4 32 = by 32								
8 = by 8 36 = by 36								
9 = by 9								
4 Size/Bits Depth								
64 = 64K 4096 = 4 MEG								
256 = 256K 8192 = 8 MEG								
1024 = 1 MEG 16384 = 16 MEG								
5 Package Type								
G = Single In-Line Package (SIP)								
S = Single In-Line Module (SIM)								
D = Dual In-Line Package (DIP)								
W = .050 inch Pitch Edge Connect								
Z = Zig-Zag In-Line Package (ZIP)								
6 Special Designation								
P = Page Mode								
N = Nibble Mode								
K = Static Column Mode								
W = Write Per Bit Mode								
V = Video Ram								
7 Separator								
- = Commercial 0°C to +70°C								
M = Military Equivalent Screened (-55°C to +125°C)								
I = Industrial Temperature Tested (-45°C to +85°C)								
X = Burned In								
8 Speed (first two significant digits)								
DRAMS SRAMS								
50 = 50 nS 8 = 8 nS								
60 = 60 nS 12 = 12 nS								
70 = 70 nS 15 = 15 nS								
80 = 80 nS 20 = 20 nS								

The numbers and coding on this page do not include all variations available but are shown as examples of the most widely used variations. Contact Accuthek if other information is required.

EXAMPLES:

AK63232Z-12

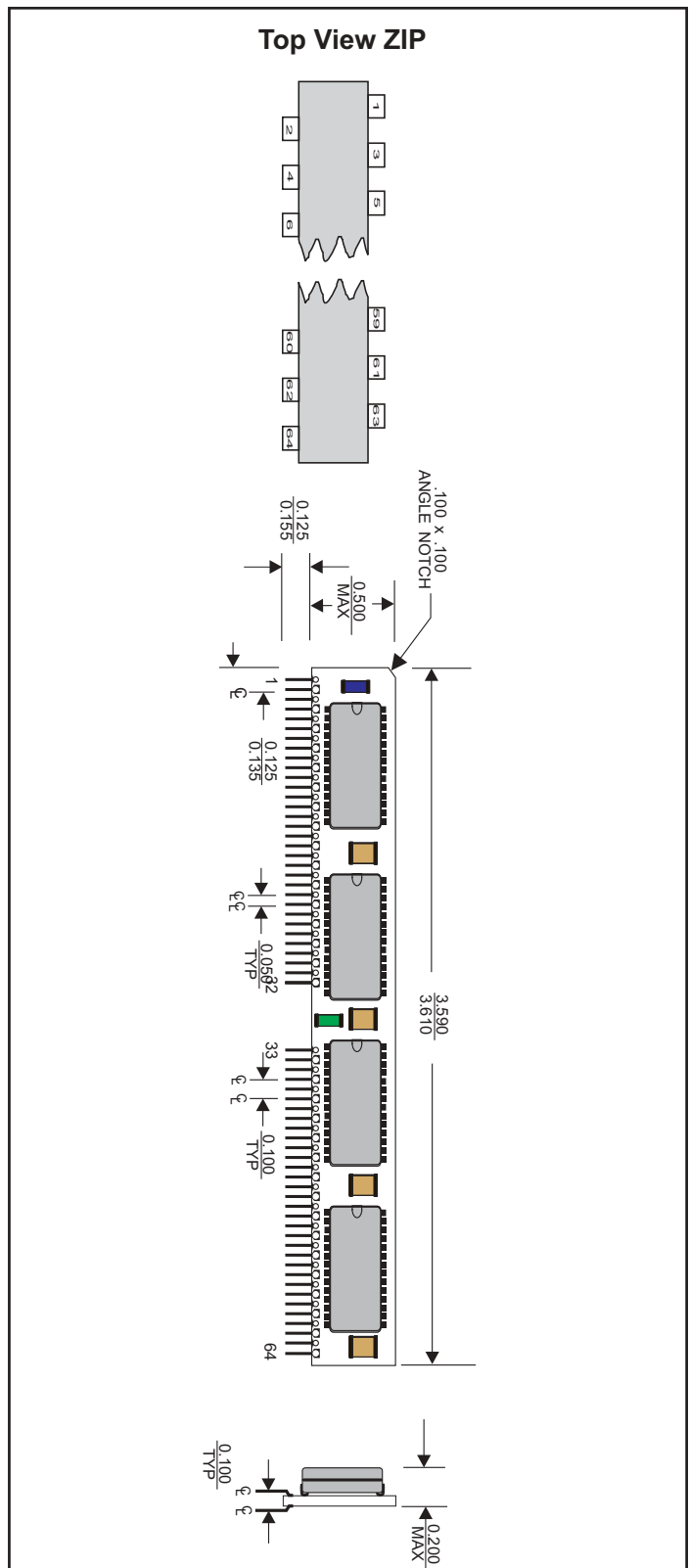
32K x 32, 12 nSEC SRAM ZIP Module



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MECHANICAL DIMENSIONS

Inches



Accuthek reserves the right to make changes in specifications at any time and without notice. Accuthek does not assume any responsibility for the use of any circuitry described; no circuit patent licenses are implied. Preliminary data sheets contain minimum and maximum limits based upon design objectives, which are subject to change upon full characterization over the specific operating conditions.